

Docket No. GNE518US
ARI.027 •

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Noboru Morita, et al.

Serial No.: Not Yet Assigned Group Art Unit: Not Yet Assigned

Filing Date: Concurrently Herewith Examiner: Unknown

For: METHOD OF FABRICATING SEMICONDUCTOR DEVICE USING
PLASMA-ENHANCED CVD

Honorable Commissioner of Patents
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:


Under the provisions of 37 CFR §1.97 through §1.99 and pursuant to applicant's duty of disclosure under 37 CFR §1.56, applicant respectfully brings the following document listed on the attached form PTO-1449, to the attention of the Examiner in charge of the above-identified application. A copy of the listed document is provided herewith for the convenience of the Examiner.

This citation does not constitute an admission that the reference is relevant or material to the claims. It is only cited as constituting related art of which the applicant is aware.

It is respectfully requested that the listed reference be considered by the Examiner and formally made of record in this application.

Please charge any deficiencies in fees and credit any overpayment of fees to Attorney's Deposit Account No. 50-0481.

Respectfully submitted,



Sean M. McGinn, Esq.
Registration No. 34,386

Date: 11/30/04
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INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)

GNE518US

Application Number

Not Yet Assigned

Applicant(s)

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U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

Junji Noguchi, et al., "TDDB Improvement in Cu Metallization under Bias Stress", 30th Annual International Reliability Physics Symposium, San Jose, CA, IEEE 2000, pp. 339-343.

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.